
Subject: *SOLVED* NIC Bonding/Grouping
Posted by [joelee](#) on Thu, 12 Jul 2007 19:10:20 GMT
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I've come across this how-to article regarding the concept of NIC Bonding or Grouping and wanted to know if OVZ supports that kind of setup. Here's a link to the article:

http://howtoforge.com/nic_bonding#comment-3628

Here's an excerpt from the article:

"The concept of NIC Bonding (or sometimes called NIC Teaming) is that you have two NICs bonded together to appear as if they are the same physical device. I.e. They will both present the same Hardware (MAC) address. This is accomplished through the ifenslave utility, which enables the kernel to see/use only one device, while it sends out packets via the two slave devices using a round-robin scheduler."

Joe

Subject: Re: NIC Bonding/Grouping
Posted by [Vasily Tarasov](#) on Fri, 13 Jul 2007 08:04:39 GMT
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You can use bonding on HN with OpenVZ, but it isn't possible to use bond device inside VE.

HTH,
Vasily

Subject: Re: NIC Bonding/Grouping
Posted by [joelee](#) on Fri, 13 Jul 2007 13:25:42 GMT
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Great! Thanks vasily...

Subject: Re: NIC Bonding/Grouping
Posted by [rudal](#) on Fri, 28 Mar 2008 07:57:31 GMT
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Is this still the case that we cant use the bond interface inside the VE?

Thanks.
